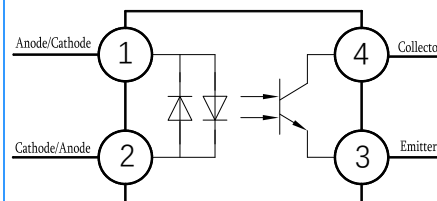


Features

- Current transfer ratio
(CTR: 20~300% at $I_F = \pm 1\text{mA}$, $V_{CE} = 5\text{V}$)
- High isolation voltage between input and output (Viso = 3750V rms)
- Collector - emitter breakdown voltage $BV_{CEO} \geq 80\text{V}$
- Operating Temperature: $-55^\circ\text{C} \sim 100^\circ\text{C}$

HF



Applications

- Switching power supply, intelligent meter
- Industrial control, measuring instruments
- Office equipment such as copiers
- Household appliances: such as air conditioners, fans, water heaters, etc.

Mechanical Data

- Case: SSOP4
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



Ordering Information

BL 3H4 (M) (G) (X) - (U) (N) (Y)

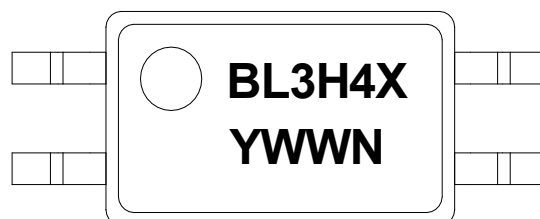
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- ① Brand(BL)
- ② Product series(3H4)
- ③ Package type(None:SSOP4)
- ④ Halogen option(None :Halogen free)
- ⑤ CTR Bank(A,B or None)
- ⑥ Lead frame (None: Copper)
- ⑦ Customer option 1 (0-9 or A-Z or none)
- ⑧ Customer option 2 (0-9 or A-Z or none)

Part Number	Package	Shipping Quantity	Marking Code
BL3H4A	SSOP4	3000 pcs / Tape & Reel	BL3H4A

Marking Information

- "BL" denotes brand.
- "3H4" denotes Product series.
- "X" denotes CTR Rank : A, B , None.
- "Y" denotes Year : A(2024), B(2025), C(2026)
- "WW" denotes Week's number .
- "N" denotes the day of Week.



Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Input	Forward Current	I _F	±50	mA
	Power Dissipation	P _D	70	mW
	Power dissipation Derating factor (above Ta = 100°C)	P _{DD}	2.9	mW/°C
	Thermal Resistance Junction-Ambient	R _{thJ-A}	325	°C/W
	Thermal Resistance Junction-Case	R _{thJ-C}	200	°C/W
Output	Power Dissipation	P _C	150	mW
	Collector Current	I _C	50	mA
	Collector-Emitter Voltage	V _{CEO}	80	V
	Emitter-Collector Voltage	V _{ECO}	7	V

Thermal Characteristics

Parameter	Symbol	Value	Unit
Total Power Dissipation	P_{TOT}	200	mW
Isolation Voltage *1	V_{ISO}	3750	V _{rms}
Operating Temperature	T_{OPR}	-55 ~ +100	°C
Storage Temperature Range	T_{STG}	-55 ~ +125	°C
Soldering Temperature *2	T_{SOL}	260	°C

Notes:

1. 40 to 60% RH, AC for 1 minute

2. For 10 seconds

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F = \pm 20\text{mA}$	-	1.2	1.4	V
	Terminal Capacitance	C_t	$V = 0, f = 1\text{kHz}$	-	30	250	pF
Output	Collector-Emitter Dark Current	I_{CEO}	$V_{CE} = 20\text{V}, I_F = 0$	-	-	100	nA
	Collector-Emitter Breakdown Voltage	BV_{CEO}	$I_C = 0.1\text{mA}, I_F = 0$	80	-	-	V
	Emitter-Collector Breakdown Voltage	BV_{ECO}	$I_E = 10\mu\text{A}, I_F = 0$	7	-	-	V
Transfer Characteristics	Current Transfer Ratio	CTR	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$	20	-	300	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F = \pm 20\text{mA}, I_C = 1\text{mA}$	-	0.1	0.2	V
	Isolation Resistance	R_{ISO}	DC500V, 40~60%R.H	5×10^{10}	1×10^{11}	-	Ω
	Floating Capacitance	C_f	$V = 0, f = 1\text{MHz}$	-	0.6	1.0	pF
	Cut-off Frequency	F_c	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$	-	80	-	kHz
	Rise Time	T_r	$V_{CE} = 2\text{V}, R_L = 100\Omega$	-	-	18	μs
	Fall Time	T_f	$I_C = 2\text{mA}$	-	-	18	

Rank Table of Current Transfer Ratio CTR

Rank Mark	Min. (%)	Max. (%)	Condition
A	50	150	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
B	100	300	
No mark	20	300	

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Fig.1 Relative Current Transfer Ratio vs Forward Current

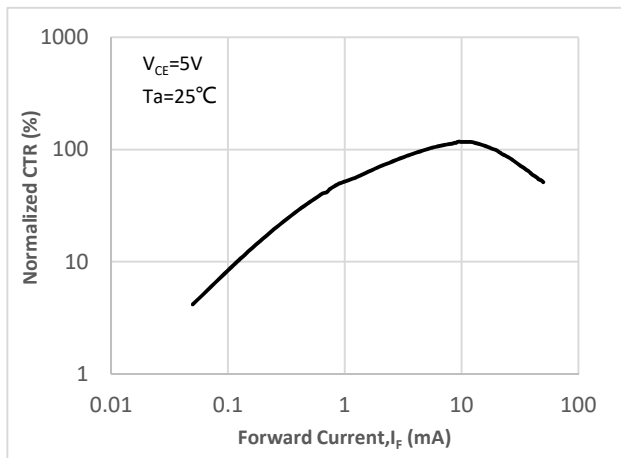


Fig.2 Forward Current vs Forward Voltage

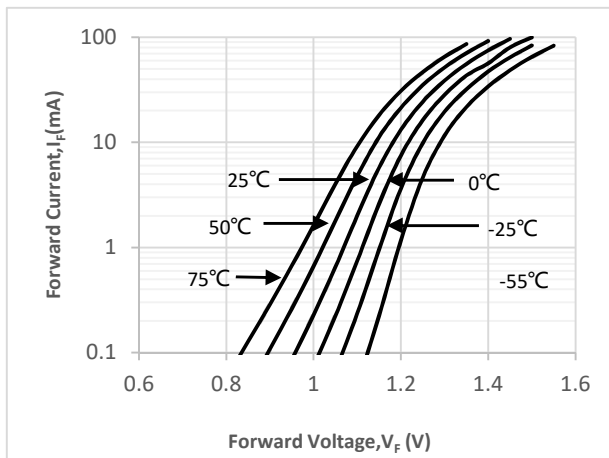


Fig.3 Collector Current vs Collector Emitter voltage

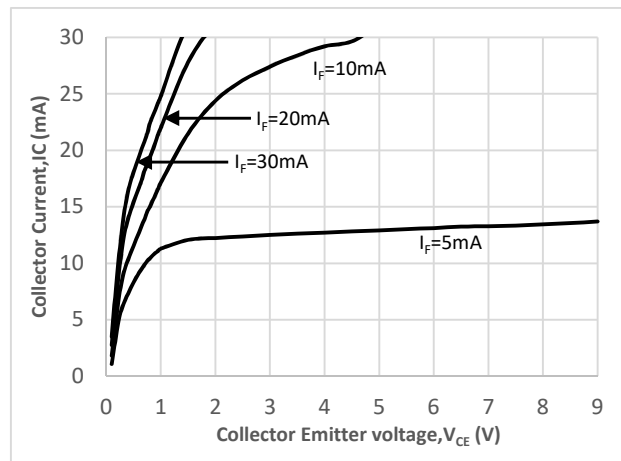


Fig.4 Relative Current Transfer Ratio vs Ambient Temperature

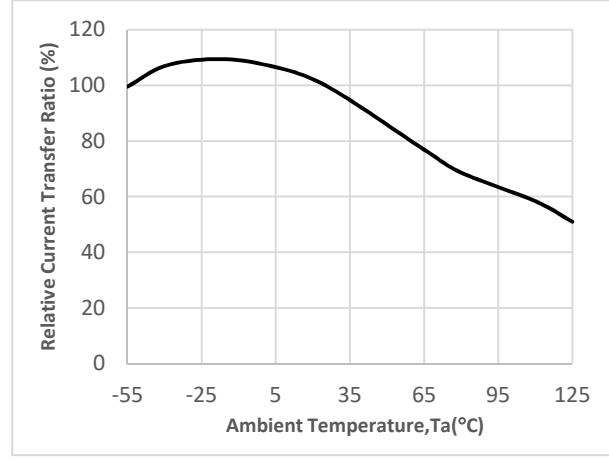


Fig.5 Collector-emitter saturation voltage vs. Ambient Temperature

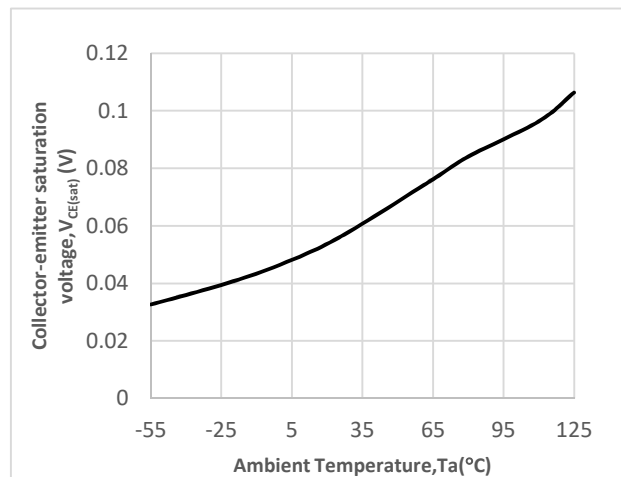


Fig.6 Collector Dark Current vs. Ambient Temperature

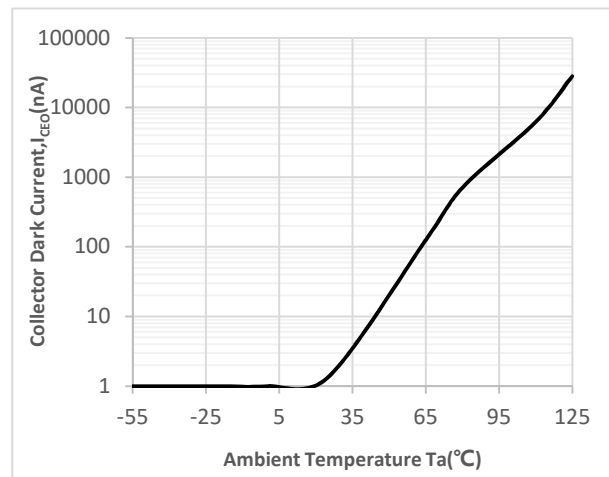


Fig.7 Response Time vs. Load Resistance

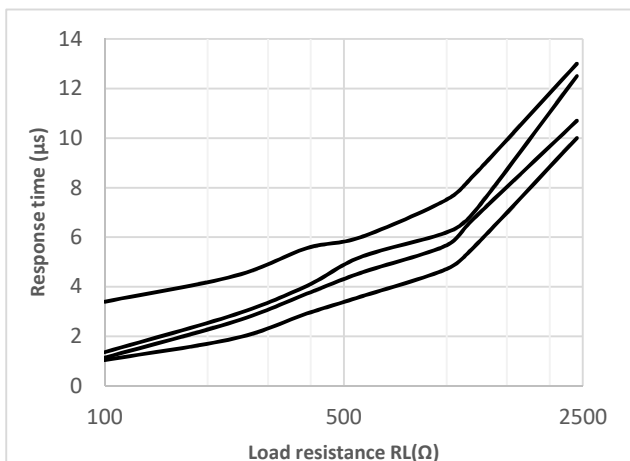


Fig.8 Frequency Response

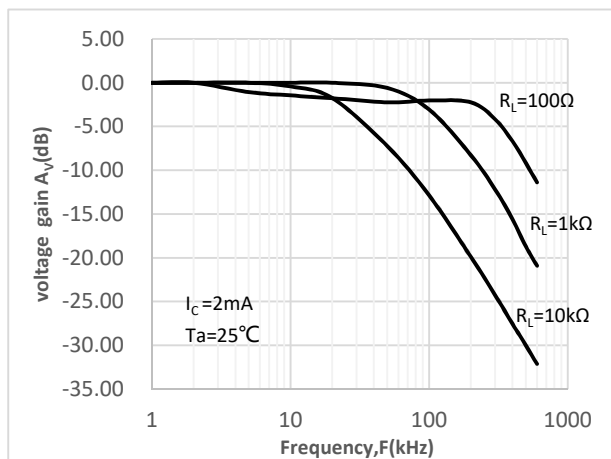


Fig.9 Collector-emitter Saturation Voltage vs. Forward Current

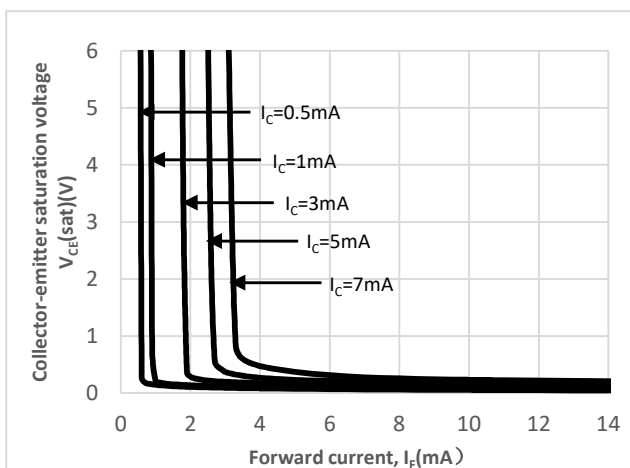
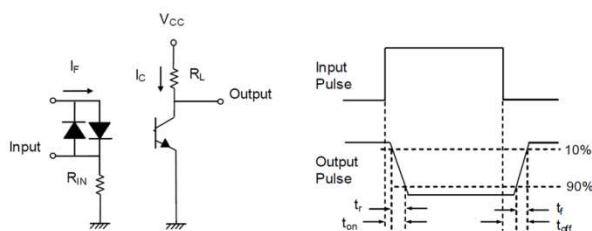
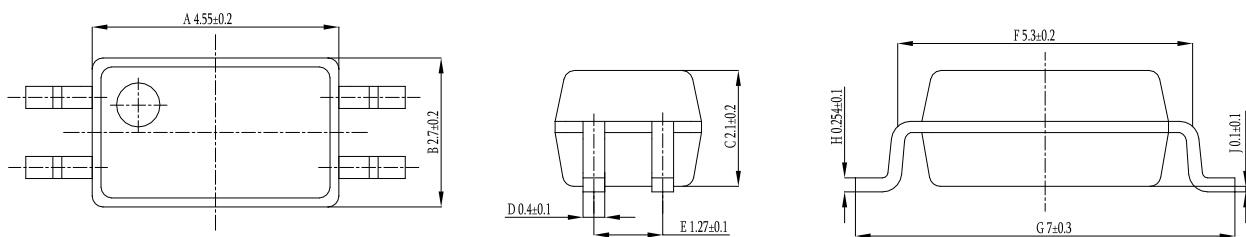


Fig.10 Switching Time Test Circuit & Waveforms

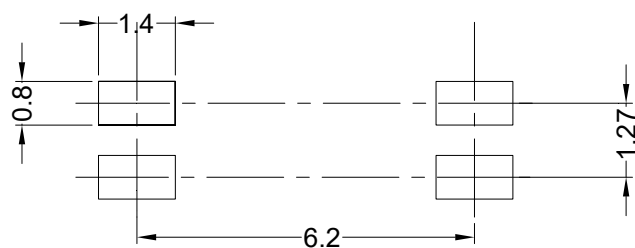


Package Outline Dimensions (unit: mm)

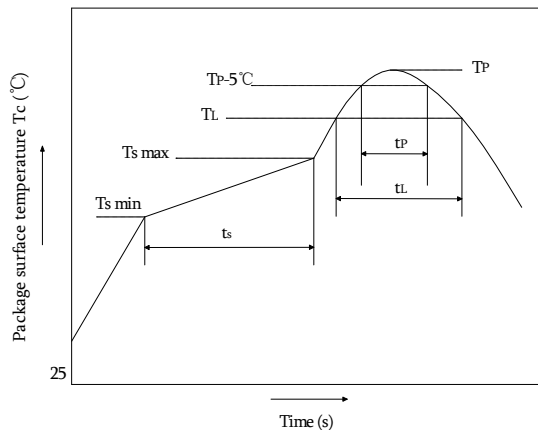
SSOP4



SOLDERING FOOTPRINT (unit: mm)



Reflow soldering

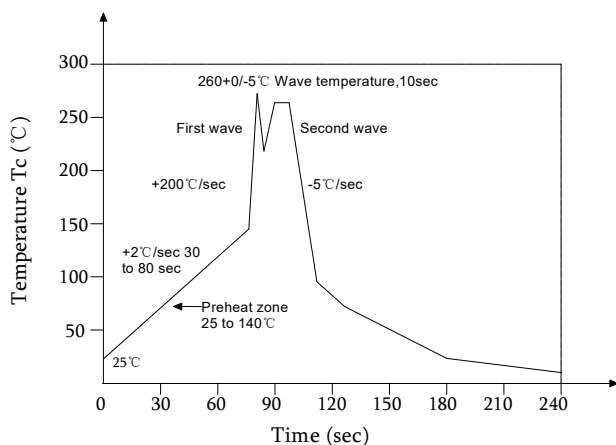


	Symbol	Min	Max	Unit
Preheat temperature	T_s	150	200	$^\circ\text{C}$
Preheat time	t_s	60	120	s
Ramp-up rate(T_L to T_P)			3	$^\circ\text{C/s}$
Liquidus temperature	T_L	217		$^\circ\text{C}$
Time above T_L	t_L	60	150	s
Peak temperature	T_p		260	$^\circ\text{C}$
Time during which T_c is between ($T_P - 5$) and T_P	t_p		30	s
Ramp-down rate(T_P to T_L)			6	$^\circ\text{C/s}$

Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.

Wave soldering



Profile feature	
Average ramp-up rate	$\sim 200^\circ\text{C/s}$
Heating rate during preheat	1°C/s to 2°C/s typical; 4°C/s maximum
Final preheat temperature T_s	$\sim 130^\circ\text{C}$
Preheat time (25°C to T_s)	$> 60\text{s}$
Peak temperature T_p	260°C
Time within peak temperature t_p	10s
Ramp-down rate	5°C/s maximum

Soldering with hand soldering iron

- Hand soldering iron is only used for product rework or sample testing.
- Hand soldering iron requirements: Temperature: $360^\circ\text{C} \pm 5^\circ\text{C}$ within 3s.

Pcaking

Package Type	Packing Form	Quantity per Tube & Reel	Quantity per Box	Quantity per Carton	Antistatic Bag Specification	Box Specification	Carton Specification	Note
SSOP4	Reel($\phi 330$ mm)	3000 pcs/reel	2 reels /box	5 boxes /ctn	380*420mm	350*340*60mm	365*330*370mm	Leave 20 Spaces at the beginning and 50 Spaces at the end

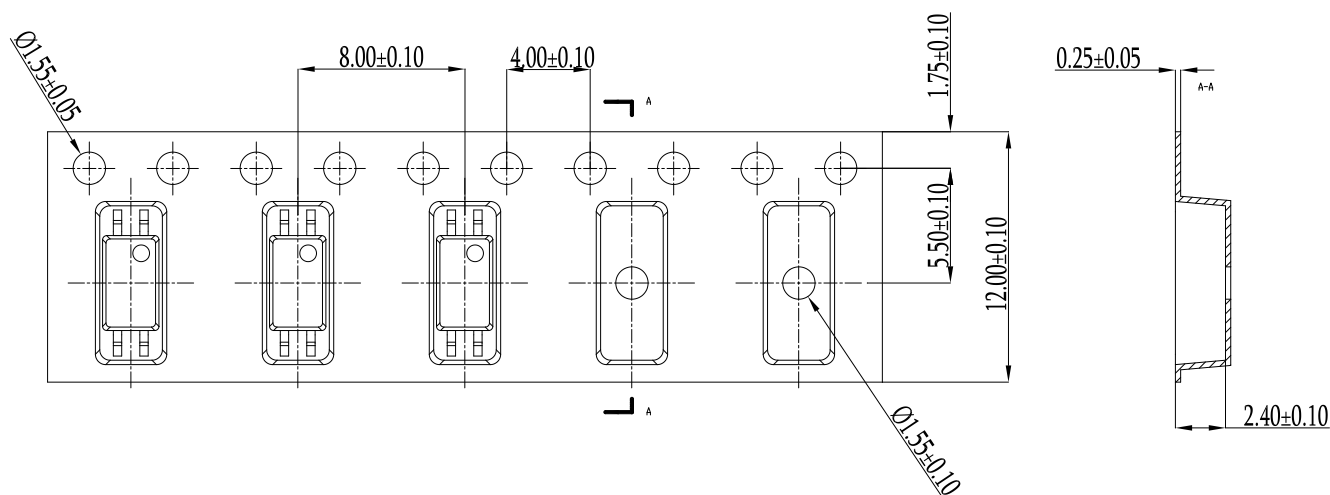
■Summary table

■SSOP4 (Reel)

Qty/reel: 3000 pcs. Qty/box: 6000 pcs.

Qty/ctn : 30000 pcs.

Schematic: (unit:mm)



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